# HOSTAFORM® C 9021 SW

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Chemical abbreviation according to ISO 1043-1: POM-KD10
Molding compound ISO 29988-POM-K,KD10,GNRS2,3-2
POM copolymer Injection molding type, special modified with anti-friction additives for prevention of squeaking noise; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. UL-registration in natural and black and a thickness more than 1.5 mm as UL 94 HB. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1,5 mm. Ranges of applications: For sliding combinations with low wear and low coefficient of friction, prevents squeaking noise. UL = Underwriters Laboratories (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

## Product information

| | | |
|---|---|---|
| Resin Identification | POM-KD10 | ISO 1043 |
| Part Marking Code | >POM-KD10< | ISO 11469 |

## Rheological properties

| | | | |
|---|---|---|---|
| Melt volume-flow rate | 6.5 | $cm^3$/10min | ISO 1133 |
| Temperature | 190 | °C | |
| Load | 2.16 | kg | |
| Moulding shrinkage, parallel | 2.1[1] | % | ISO 294-4, 2577 |
| Moulding shrinkage, normal | 1.7[1] | % | ISO 294-4, 2577 |

[1]: @ 195°C

## Typical mechanical properties

| | | | |
|---|---|---|---|
| Tensile modulus | 2850 | MPa | ISO 527-1/-2 |
| Tensile stress at yield, 50mm/min | 53 | MPa | ISO 527-1/-2 |
| Tensile strain at yield, 50mm/min | 7 | % | ISO 527-1/-2 |
| Nominal strain at break | 16 | % | ISO 527-1/-2 |
| Tensile creep modulus, 1h | 2400 | MPa | ISO 899-1 |
| Tensile creep modulus, 1000h | 1200 | MPa | ISO 899-1 |
| Charpy impact strength, 23°C | 90 | $kJ/m^2$ | ISO 179/1eU |
| Charpy impact strength, -30°C | 85 | $kJ/m^2$ | ISO 179/1eU |
| Charpy notched impact strength, 23°C | 4 | $kJ/m^2$ | ISO 179/1eA |
| Charpy notched impact strength, -30°C | 4 | $kJ/m^2$ | ISO 179/1eA |
| Ball indentation hardness, H 358/30 | 135 | MPa | ISO 2039-1 |
| Poisson's ratio | 0.37[C] | | |

[C]: Calculated

## Thermal properties

| | | | |
|---|---|---|---|
| Melting temperature, 10°C/min | 166 | °C | ISO 11357-1/-3 |
| Temperature of deflection under load, 1.8 MPa | 80 | °C | ISO 75-1/-2 |
| Coefficient of linear thermal expansion (CLTE), parallel | 120 | E-6/K | ISO 11359-1/-2 |

## Flammability

| | | | |
|---|---|---|---|
| Burning Behav. at 1.5mm nom. thickn. | HB | class | IEC 60695-11-10 |
| Thickness tested | 1.6 | mm | IEC 60695-11-10 |
| Burning Behav. at thickness h | HB | class | IEC 60695-11-10 |
| Thickness tested | 3.18 | mm | IEC 60695-11-10 |
| UL recognition | yes | | UL 94 |

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## Electrical properties

| | | | |
|---|---|---|---|
| Relative permittivity, 100Hz | 4.1 | | IEC 62631-2-1 |
| Relative permittivity, 1MHz | 4.1 | | IEC 62631-2-1 |
| Dissipation factor, 100Hz | 35 | E-4 | IEC 62631-2-1 |
| Dissipation factor, 1MHz | 75 | E-4 | IEC 62631-2-1 |
| Volume resistivity | 1E12 | Ohm.m | IEC 62631-3-1 |
| Surface resistivity | 1E14 | Ohm | IEC 62631-3-2 |
| Comparative tracking index | 600 | | IEC 60112 |

## Physical/Other properties

| | | | |
|---|---|---|---|
| Humidity absorption, 2mm | 0.2 | % | Sim. to ISO 62 |
| Water absorption, 2mm | 1.2 | % | Sim. to ISO 62 |
| Density | 1420 | kg/m³ | ISO 1183 |

## Injection

| | | |
|---|---|---|
| Drying Recommended | no | |
| Drying Temperature | 100 | °C |
| Drying Time, Dehumidified Dryer | 3 - 4 | h |
| Processing Moisture Content | ≤0.2 | % |
| Melt Temperature Optimum | 200 | °C |
| Min. melt temperature | 190 | °C |
| Max. melt temperature | 210 | °C |
| Screw tangential speed | ≤0.3 | m/s |
| Mold Temperature Optimum | 100 | °C |
| Min. mould temperature | 80 | °C |
| Max. mould temperature | 120 | °C |
| Hold pressure range | 60 - 120 | MPa |
| Back pressure | 2 | MPa |

## Characteristics

| | |
|---|---|
| Processing | Injection Moulding, Other Extrusion |
| Delivery form | Pellets |
| Additives | Release agent |
| Special characteristics | Low wear / Low friction |

## Additional information

Injection molding

### Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

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Processing Notes

## Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

## Postprocessing

Conditioning e.g. moisturizing is not necessary.

## Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

## Storage

The product can then be stored in standard conditions until processed.

## Automotive

| OEM | STANDARD | ADDITIONAL INFORMATION |
|---|---|---|
| Bosch | N28 BN22-O015 | Natural |
| Bosch | N28 BN22-O015 | Black |
| Continental | TST N 055 54.23 | |
| Hyundai | MS237-05 Type A-2 | |
| Nissan | POM(0xx)-Ixx-1 | |

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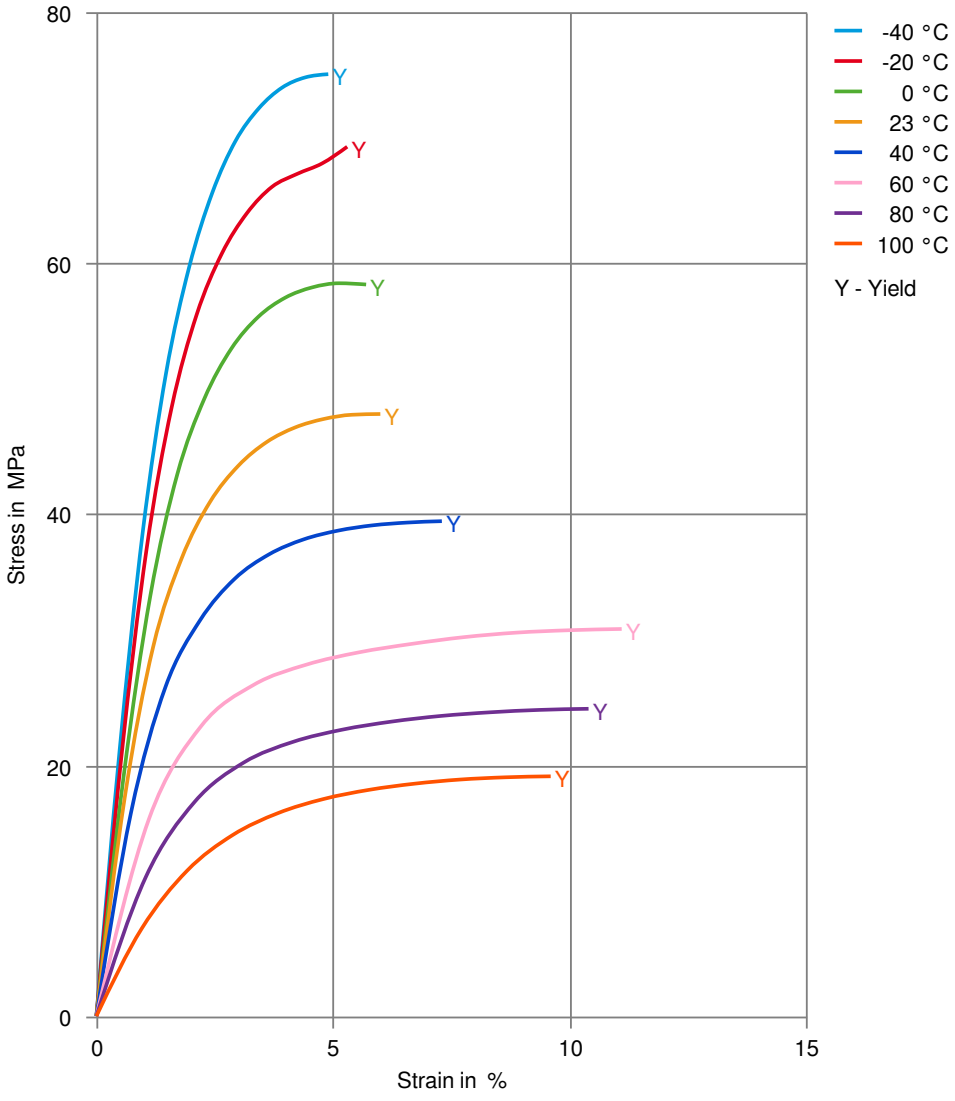
## Stress-strain



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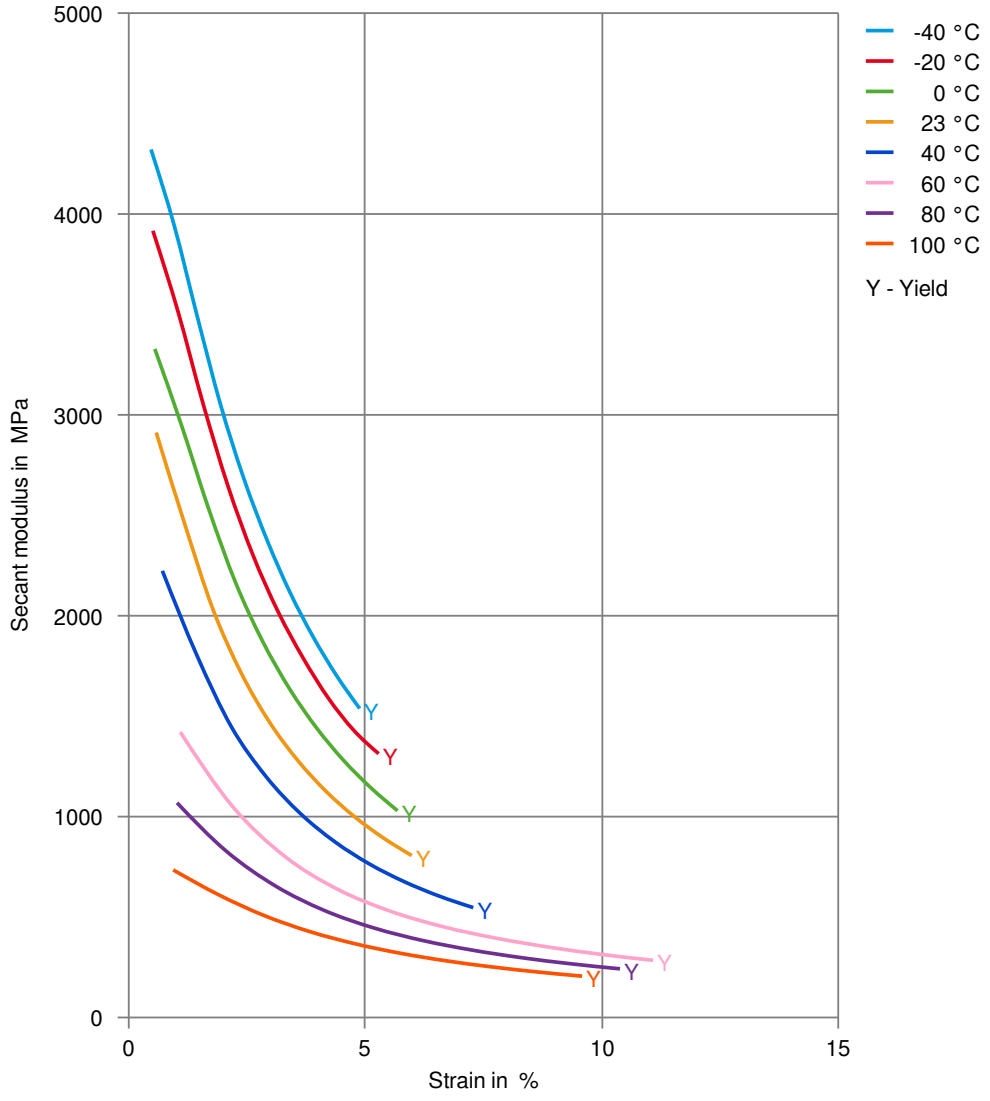
## Secant modulus-strain



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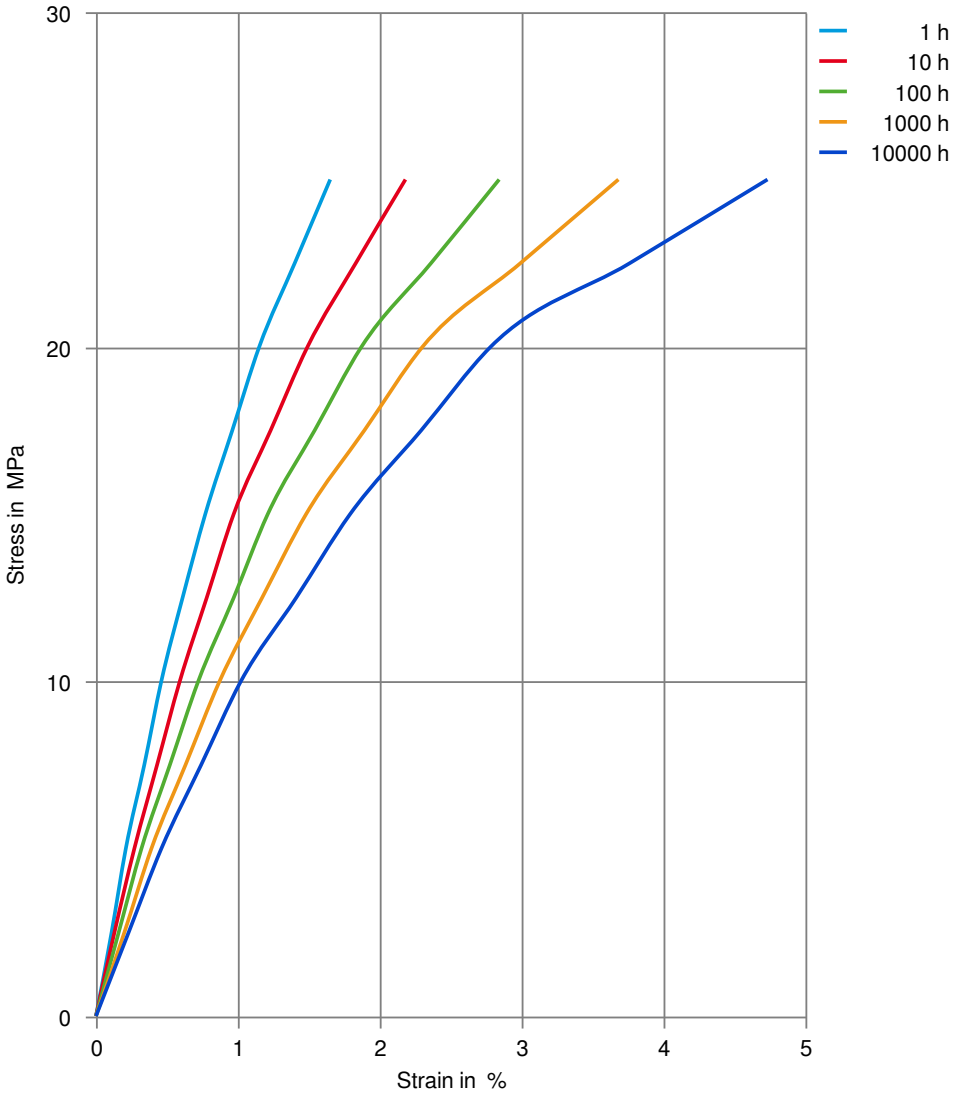
## Stress-strain (isochronous) 23 °C



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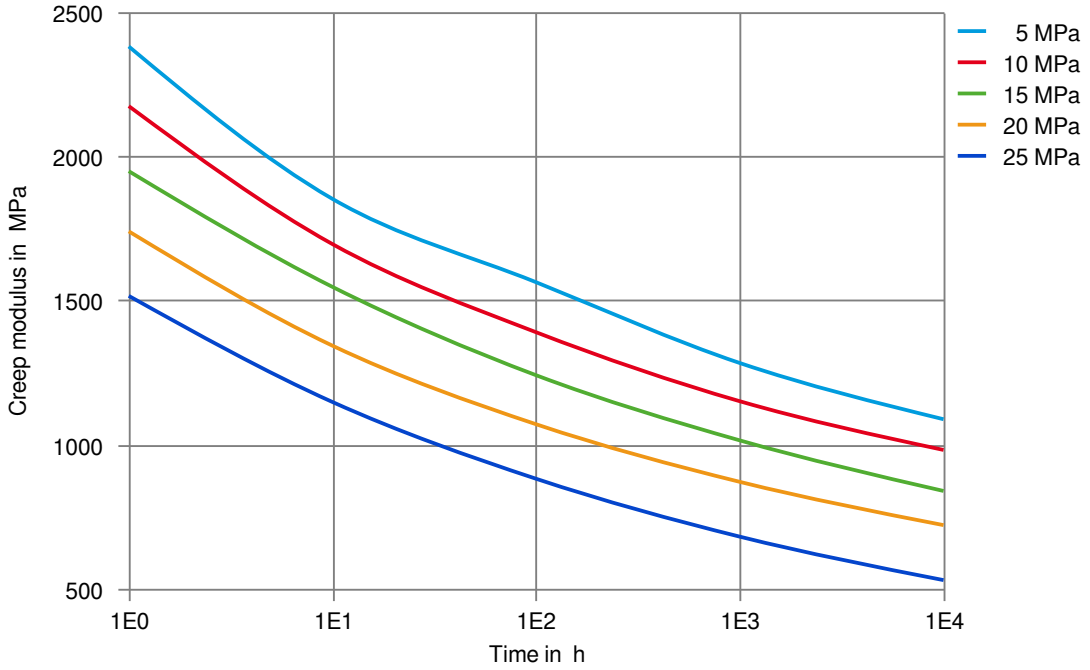
## Creep modulus-time 23 °C



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